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AMENDMENTS TO THE CLAIMS

12. (Currently amended) A device for interconnecting a plurality of circuit devices, comprising:  
a decoupling capacitor mounted on a first surface and having a grounding pad and  
a power pad formed on a top surface of said decoupling capacitor; and  
an interconnect layer having a pattern of circuit connections and being formed  
over said top surface of said decoupling capacitor, whereby electrical connections to ef  
said decoupling capacitor are embedded within said interconnect layer and said  
interconnect layer is disposed between said decoupling capacitor and said plurality of  
circuit devices,  
and whereby said pattern of circuit connections of said interconnect layer is  
coupled to said decoupling capacitor and said plurality of circuit devices, said pattern of  
circuit connections coupling to said grounding pad and said power pad of said decoupling  
capacitor.

21. (Previously amended) The device according to claim 12, wherein said pattern of circuit  
connections includes at least one of the following to interconnect said plurality of circuit  
devices: a signal plane, a power plane and a ground plane.

22. (Previously added) The device according to claim 12, wherein said interconnect layer  
includes a power plane and a ground plane, and wherein said decoupling capacitor  
connects in parallel between said power and ground planes.

23. (Cancelled)

24. (Previously added) The device according to claim 12, wherein said decoupling capacitor  
comprises a silicon containing dielectric material.

25. (Previously added) The device according to claim 12, wherein said interconnecting layer  
comprises a plurality of aluminum containing conductive paths.

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26. (Previously added) The device according to claim 12, wherein said interconnecting layer comprises a plurality of copper containing conductive paths.
27. (Previously added) The device according to claim 12, wherein said decoupling capacitor comprises a silicon base die decoupling capacitor.
28. (Previously added) The device according to claim 12, said decoupling capacitor having a capacitance in the range of 1 to 1000  $\text{nf/cm}^2$ .
29. (Previously added) The device according to claim 28, said decoupling capacitor having a capacitance of approximately 50  $\text{nf/cm}^2$ .
30. (Previously added) The device according to claim 12, further comprising a plurality of decoupling capacitors mounted on said first surface.
31. (Previously added) The device according to claim 12, further comprises at least one resistor mounted on said first surface.
32. (Currently amended) The device according to claim 12 30, wherein each of said plurality of circuit devices is are in electrical communication with at least one of said decoupling capacitors.
33. (Cancelled)